WAMD

Workshop on Advanced Materials and Devices

November 4-6 2015 Hotel Krystal Ixtapa-Zihuatanejo, Mexico

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2015 IEEE Autumn Meeting on Power, Electronics and Computing

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Dear Colleagues:

On behalf of the Organizing Committee for the 2nd Workshop on Advanced Material and Devices (WAMD 2015), I want to express our gratitude for your presence and contribution to this conference.

WAMD is a organized in Latin America by a group of members of the Electron Device Society of the IEEE, with the objective of contributing and stimulating higher education and technical development in the region by gathering top experts in the field in an international conference to be held in the region. The first edition took place in Havana Cuba, on March 2013, where participants agreed to celebrate it every 2 years.

Next November we will meet again in Ixtapa-Zihuatanejo, Mexico, as a special session inside a well known IEEE conference held every year in Mexico, the IEEE International Autumn Meeting on Power, Electronics and Computing (ROPEC). We hope that the excellent, relaxing and beautiful conditions of the location will contribute to the discussion of new results and ideas, as well as meeting new colleagues and establishing collaborations in the field.

The conference will consist of Plenary Keynotes and contributions presenting relevant ideas or innovations in the areas of Advanced Materials, Electron Devices and Electronics. All submissions will undergo a review procedure, and accepted papers will be published in ROPEC Proceedings, and will be available via IEEE Xplore.

General information regarding manuscript submission, important dates, conference fees, local accommodation can be found at the ROPEC page at http://ropec.org

Sincerely yours,

Dr. Arturo Escobosa General Chair

